

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2013/09/06	Jamie Zie
A1			Change	2016/04/01	Phebe Su
A2			Add DIM	2016/05/04	Phebe Su
A3			Change shell plating	2018/03/20	Phebe Su
A4			Modify the shell	2020/11/27	Ginny Liao
A5			Change Dim	2021/01/08	Ginny Liao
A6			Change Dim	2021/10/19	Ken Lin
A7			Add Notes.	2025/01/20	Ken Lin

NOTES:

1.MATERIAL:

- 1.1 HOUSING: HIGH TEMPERATURE THERAL PLASTIC, LCP COLOR:BLACK
- 1.2 CONTACT: COPPER ALLOY.
- 1.3 SHELL: COPPER ALLOY/SPCC .

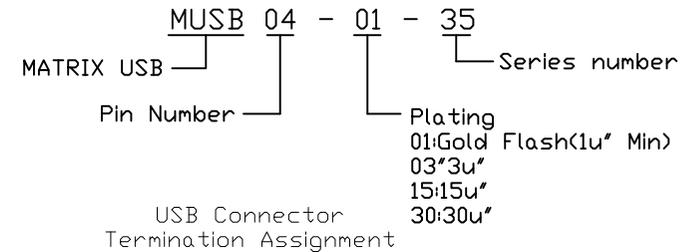
2.FINISH:

- 2.1 CONTACT: G/F IN CONTACT AREA/100u" MIN TIN IN SOLDER AREA,50u" MIN. NICKEL UNDERPLATING OVER ALL.
- 2.2 SHELL: SOLDERABILITY NICKEL PLATING OVER ALL.

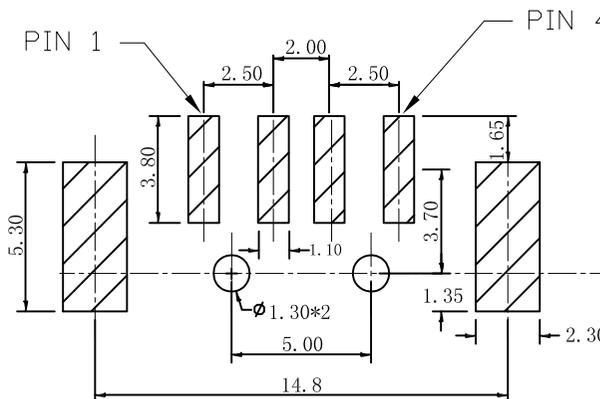
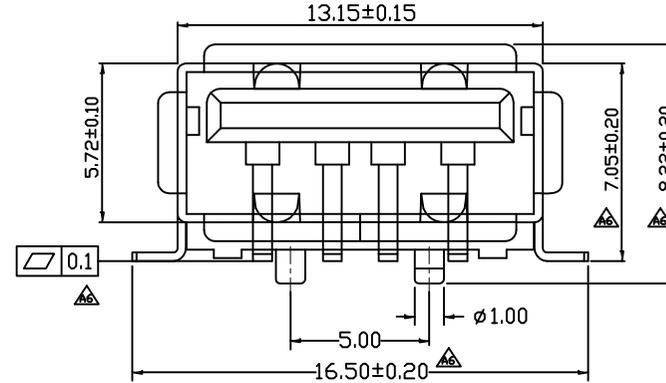
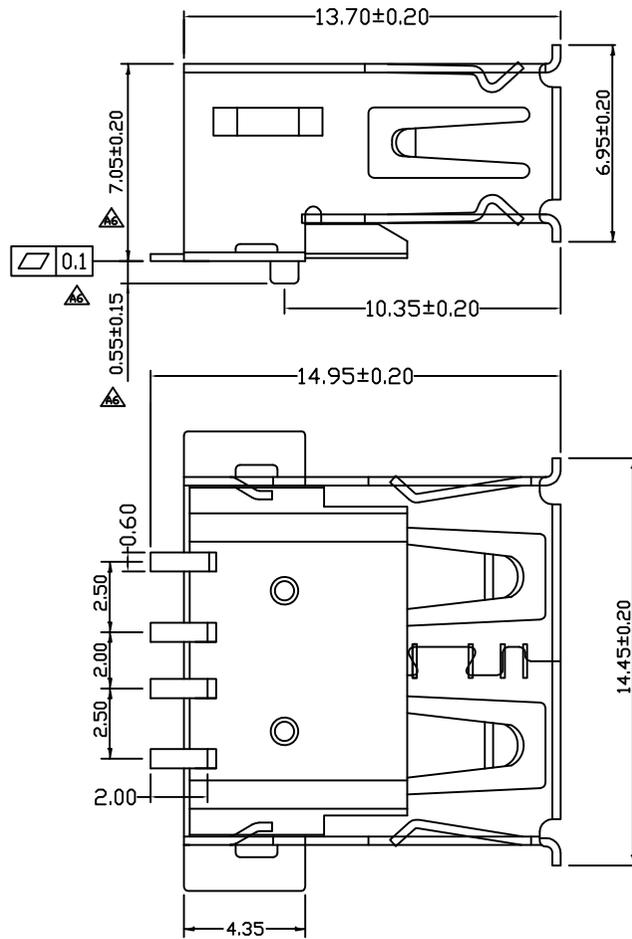
3. ENVIRONMENT:

OPERATING TEMPERATURE-40°C~+95°C

MATRIX PART NO:



Contact Number	Signal Name
1	VBUS
2	D-
3	D+
4	GND

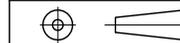


RECOMMENED PCB LAYOUT
TOLERANCE : ±0.05
(TOP VIEW)



Matrix Electronics Co.,Ltd

TOLERANCE: X:X ±0.25 X:XX ±0.20 X:XXX ±0.15 X:XXX ±0.05 ANGLE: ±3°		DESIGN BY : Ken Lin	DATE : 2025/01/20	PART NAME: USB 2.0 AF, SMT type	
		CHECKED BY: Vicky Hsieh	DATE : 2025/01/20	PART NO.	MUSB04-01-35
		APPROVED BY1: Richard Hsieh	DATE : 2025/01/20	MOLD NO.	NA
		APPROVED BY2: Richard Hsieh	DATE : 2025/01/20	DRAW NO.	
SCALE:1:1	SIZE:A4			SHEET NO.	1 OF 1



UNIT: mm [inch]